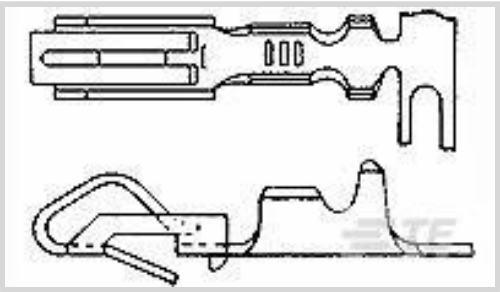




Connectors > Contacts > Connector Contacts



Contact Type: **Hermaphroditic**
Contact Mating Area Plating Material: **Gold**
Contact Retention Type Within Housing: **Snap-In**
Wire Size: **.2 – .8 mm²**

Features

Packaging Features

Packaging Method	Loose Piece
Packaging Quantity	1000

Dimensions

Compatible Insulation Diameter Range	2.54 mm[.1 in]
Wire Size	.2 – .8 mm ²

Mechanical Attachment

Wire Insulation Support	With
PCB Mount Retention	Without
Contact Retention Type Within Housing	Snap-In

Contact Features

Contact Orientation	Straight
PCB Contact Termination Area Plating Material	Nickel
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Hermaphroditic
Contact Mating Area Plating Material	Gold
Contact Base Material	Phosphor Bronze
Contact Current Rating (Max)	6 A

Termination Features

Termination Method to Wire & Cable	Crimp
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Product Terminates To	Wire & Cable
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Signal
Other	
EU ELV Compliance	Compliant

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Out of Scope
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Not reviewed for China RoHS compliance
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 640136-2
02P EDGE CONN HSG, BIF-LEAF

TE Part # 91597-1
CCII SL-156 REC 24-18 ASSY

Customers Also Bought

TE Part #1-640383-0
10P MTA156 HDR ASSY STR SQ SN

TE Part #3-61668-1
BIF-LEAF CONT CR/SNAP SN/BR

TE Part #61668-4
BIF-LEAF CONT CR/SNAP AUPHBZ

TE Part #350980-3
.045 POST CONTACT AUPLBR

TE Part #1241959-4
STD-TIM HSG MKII 4P

TE Part #316769-2
POWER D/LOCK CAP HSG 1P RED

TE Part #1802110-2
COVER,MATENET SEALED PROTECTION, STP

TE Part #1802112-2
MATENET SWS FOR UTP-STP

TE Part #2154828-2
Cable Assembly EPII 3 Pos

TE Part #2154828-3
Cable Assembly EPII 4 Pos

Documents

Product Drawings

BIF-LEAF CONT AUPHBZ LP 24-18

English

CAD Files

Customer View Model

ENG_CVM_350011-2_J.3d_igs.zip

English

Customer View Model



[ENG_CVM_350011-2_J.3d_stp.zip](#)

English

Customer View Model

[ENG_CVM_350011-2_J.2d_dxf.zip](#)

English

3D PDF

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Bifurcated Leaf Contact

English

Application Specification

English